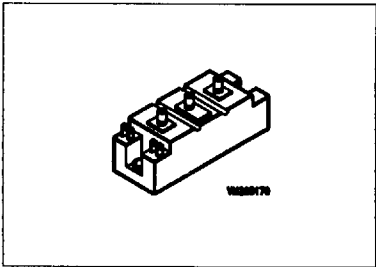


IGBT Module® 500gb16a doc

$V_{CE} = 1600\text{ V}$
 $I_C = 2 \times 70\text{ A at } T_C = 25^\circ\text{C}$
 $I_C = 2 \times 50\text{ A at } T_C = 80^\circ\text{C}$

- Power module
- Half-bridge
- Including fast free-wheel diodes
- Package with insulated metal base plate



Half-bridge			
Type	Ordering code	Type	Ordering code
BSM 50 GB 160D	C67076-A2111-A2		

Maximum Ratings

Parameter		Symbol	Values	Unit
Collector emitter voltage		V_{CE}	1600	V
Collector gate voltage, $R_{GE}=20\text{k}\Omega$		V_{CGR}	1600	
Gate-Emitter voltage		V_{GE}	± 20	
Continuous collector current	$T_C=25^\circ\text{C}$	I_C	70	A
	$T_C=80^\circ\text{C}$		50	
Pulsed collector current	$T_C=25^\circ\text{C}$	$I_C \text{ puls}$	140	
	$T_C=80^\circ\text{C}$		100	
Operating and storage temperature range		T_j, T_{stg}	$-55...+150$	$^\circ\text{C}$
Power dissipation, $T_C = 25^\circ\text{C}$		P_{tot}	500	W
Thermal resistance, chip-case		R_{thJC}	≤ 0.25	K/W
Insulation test voltage ¹⁾ , $t=1\text{min.}$		V_{is}	4000	V _{ac}
Creepage distance	-		16	mm
Clearance	-		11	
DIN humidity category, DIN 40 040	-		F	--
IEC climatic category, DIN IEC 68-1	-		55/150/56	

¹⁾Insulation test voltage between collector and metal base plate referred to standard climate
23/50 in acc.with DIN 50 014, IEC, para 492.1

Electrical Characteristics

Parameter and conditions at $T_j = 25^\circ\text{C}$, unless otherwise specified	Symbol	Values			Unit
		min	typ	max	

Static Characteristics

Collector-emitter breakdown voltage $V_{GE}=0, I_C=1\text{mA}$	$V_{(BR)CES}$	1600	-	-	V
Gate threshold voltage $V_{GE}=V_{CE}, I_C=4\text{mA}$	$V_{GE(th)}$	4.8	5.5	6.2	
Collector-emitter saturation voltage $V_{GE}=15\text{V}, I_C=50\text{A}$ $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$ $T_j = 150^\circ\text{C}$	$V_{CE(sat)}$	--	3.5 4.2 4.4	--	
Zero gate voltage collector current $V_{CE}=1600\text{V}, V_{GE}=0\text{V}$ $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	I_{CES}	--	500 4500	--	
Gate-emitter leakage current $V_{GE}=25\text{V}, V_{CE}=0\text{V}$	I_{CES}	--	--	100	nA

AC Characteristics

Forward transconductance $V_{CE}=20\text{V}, I_C=50\text{A}$	g_{fs}	18	--	--	S
Input capacitance $V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}$	C_{iss}	--	8	--	nF
Output capacitance $V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}$	C_{oss}	--	0.64	--	
Reverse transfer capacitance $V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}$	C_{rss}	--	0.25	--	

Parameter and conditions at $T_j = 25^\circ\text{C}$, unless otherwise specified	Symbol	Values			Unit
		min	typ	max	

Switching Characteristics, Inductive Load**at $T_j=125^\circ\text{C}$**

Turn on delay time $V_{CC}=1200\text{V}, V_{GE}=+15\text{V}, I_C=50\text{ A}$ $R_{G(on)}=47\Omega$	$t_{d(on)}$	--	0.35	--	μs
Rise time $V_{CC}=1200\text{V}, V_{GE}=+15\text{V}, I_C=50\text{ A}$ $R_{G(on)}=47\Omega$	t_r	--	0.15	--	μs
Turn off delay time $V_{CC}=1200\text{V}, V_{GE}=-15\text{V}, I_C=50\text{ A}$ $R_{G(off)}=3.3\Omega$	$t_{d(off)}$	--	0.6	--	μs
Fall time $V_{CC}=1200\text{V}, V_{GE}=-15\text{V}, I_C=50\text{ A}$ $R_{G(off)}=3.3\Omega$	t_f	--	0.05	--	μs

Free-Wheel Diode

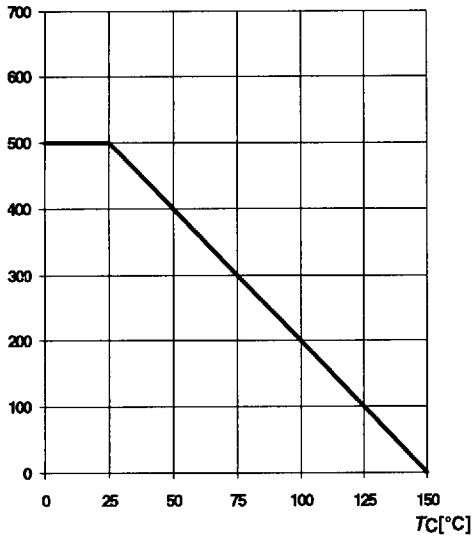
Diode forward voltage $I_F=50\text{ A}, V_{GE}=0\text{V}$ $T_j=25^\circ\text{C}$ $T_j=125^\circ\text{C}$	V_F	-- --	4.2 3.8	-- --	V
Reverse recovery time $I_F=50\text{ A}, V_R=-1200\text{V}$ $V_{GE}=0\text{V}, di_F/dt=-500\text{A}/\mu\text{s}$ $T_j=125^\circ\text{C}$	t_{rr}	--	0.5	--	μs
Reverse recovery Charge $I_F=50\text{ A}, V_R=-1200\text{V}$ $V_{GE}=0\text{V}, di_F/dt=-500\text{A}/\mu\text{s}$ $T_j=125^\circ\text{C}$	Q_{rr}	--	25	--	μC
Thermal resistance Chip-Case	R_{thJC}	--	--	0.9	K/W

Power dissipation

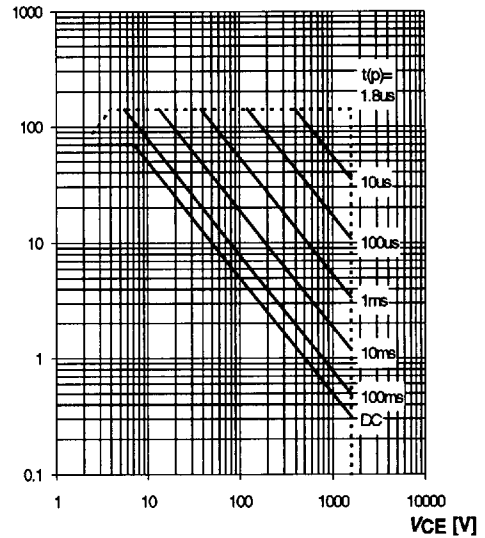
$$P_{\text{tot}} = f(T_C)$$

 P_{tot} [W]

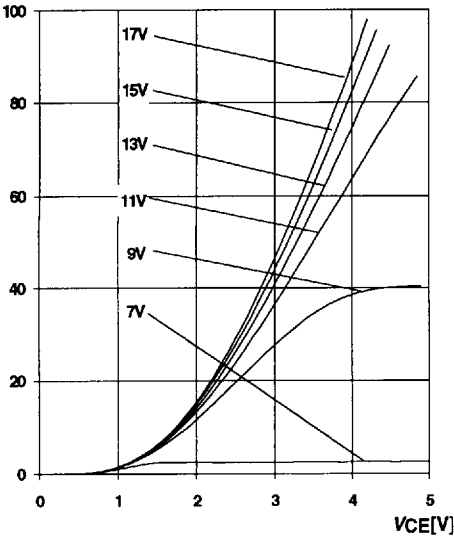
501pt.xlc

**Safe operating area $I_C = f(V_{CE})$** parameter: single pulse, $T_C = 25^\circ\text{C}$, $T_J \leq 150^\circ\text{C}$ I_C [A]

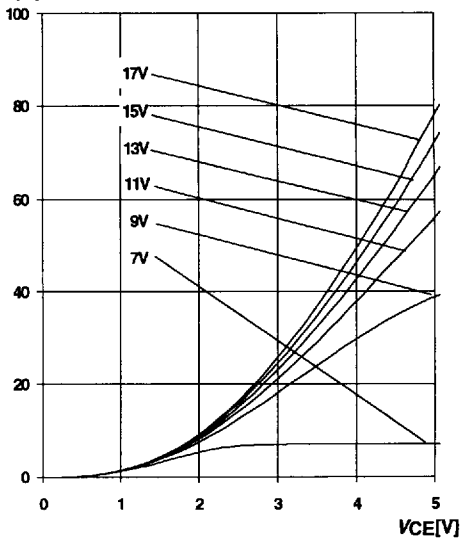
501tu.xlc

**Typ output characteristics $I_C = f(V_{CE})$** parameter: $t_p = 80 \mu\text{s}$; $T_J = 25^\circ\text{C}$ I_C [A]

501us3.xlc

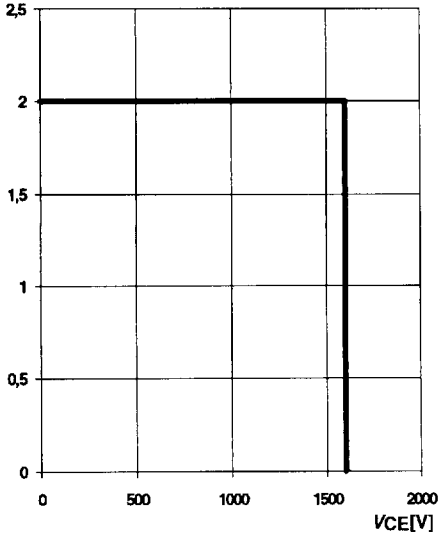
**Typ output characteristics $I_C = f(V_{CE})$** parameter: $t_p = 80 \mu\text{s}$; $T_J < 125^\circ\text{C}$ I_C [A]

501us7.xlc

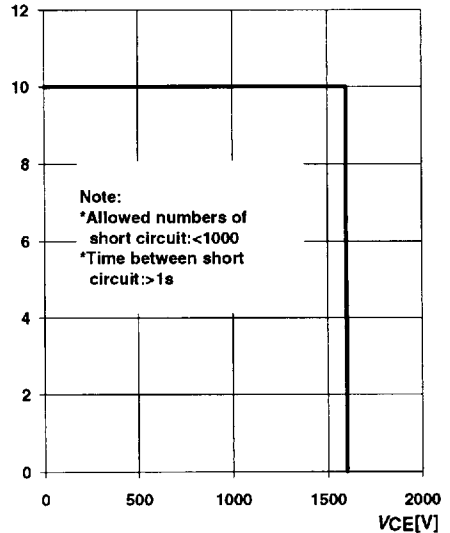


Reverse biased safe operating area $I_C = f(V_{CE})$, parameter: $T_J = 150^\circ\text{C}$ $V_{GE} = 15\text{V}$, $R_{g(\text{off})} = 3.3\Omega$ $I_{C\text{puls}}/I_C$

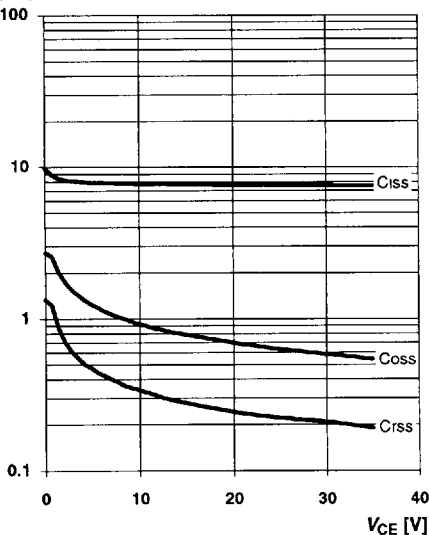
501rso xlc

**Safe operating area, SHORT CIRCUIT** $I_C = f(V_{CE})$, $V_{GE} = \pm 15\text{V}$, $T_J \leq 150^\circ\text{C}$ $t_{sc} \leq 10\mu\text{s}$, $L < 50\text{nH}$ I_{CSC}/I_{CN}

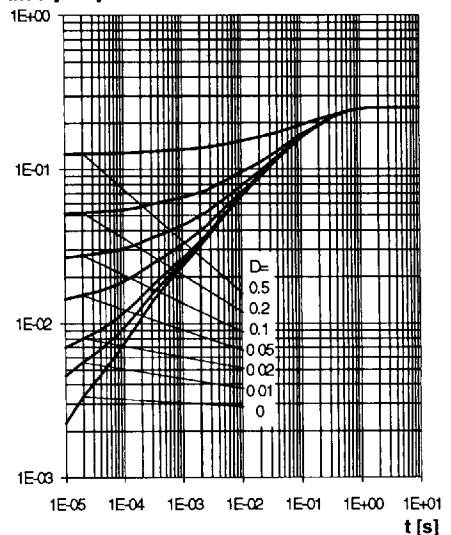
501soas xlc

**Typ. capacitances**Parameter: $V_{GE} = 0$, $f = 1\text{ MHz}$ C [nF]

501C xlc

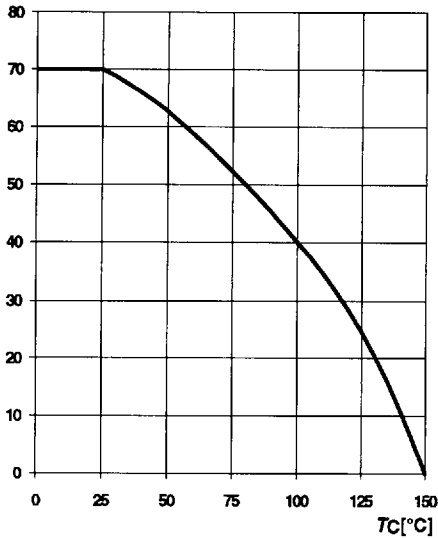
**Transient thermal impedance** $Z_{thJC} = f(t_p)$, parameter: $D = t_p/T$ Z_{thJC} [K/W]

501zth xlc

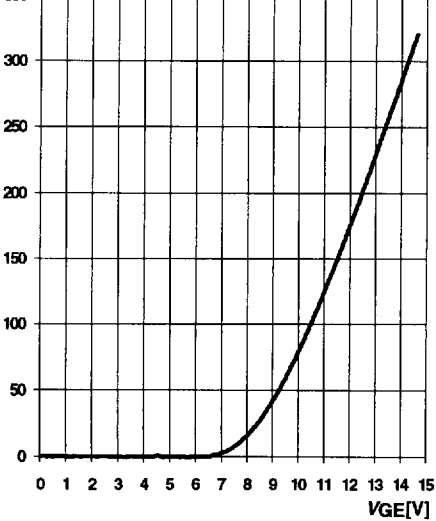


Collector current $I_C = f(T_C)$ parameter: $V_{GE} \geq 15V, T_J = 150^\circ$ **$I_C [A]$**

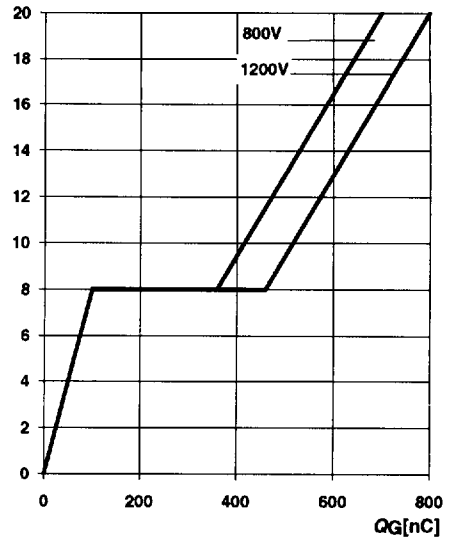
501f1 xlc

**Typ. transfer characteristics $I_C = f(V_{GE})$** parameter: $t_p = 80\mu s, V_{CE} = 20V$ **$I_C [A]$**

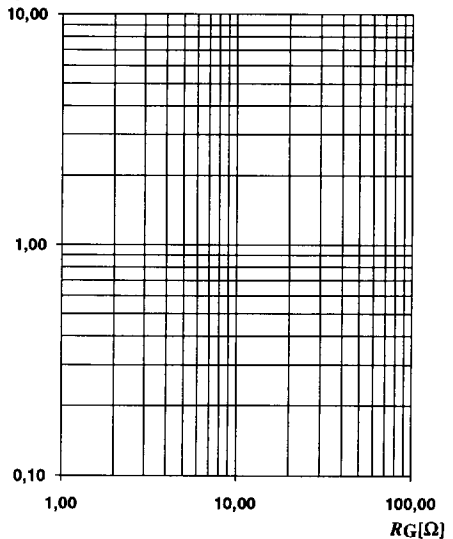
501g13 xlc

**Typ. gate charge, $V_{GE} = f(Q_G)$** **$V_{GE} [V]$**

501Qg3 xlc

**Typ. switching time $t = f(R_G)$ Inductive load**parameter: $T_J = 125^\circ C, V_{CE} = 1200V, V_{GE} = \pm 15V$ **$t [\mu s]$**

5011ng xlc

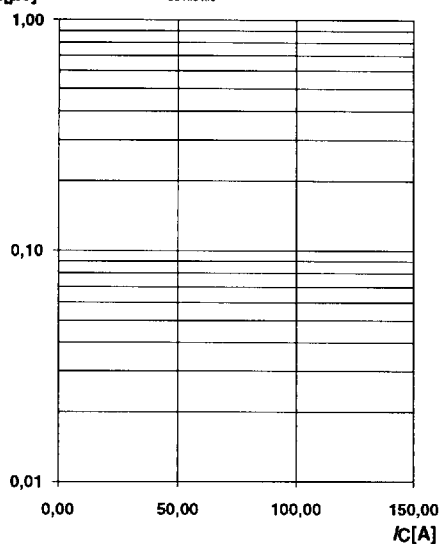


Typ. switching time $t_{\text{sw}}(I_C)$

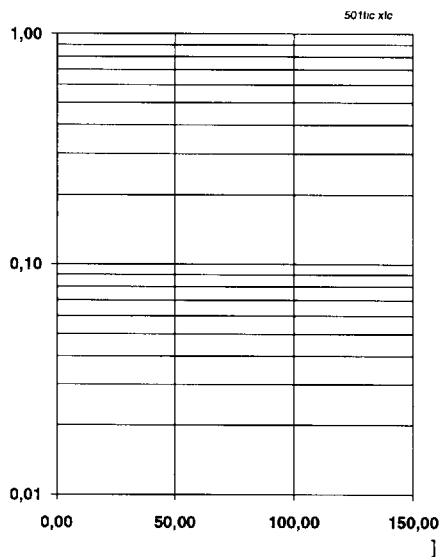
Inductive load, parameter: $T_J=125^\circ\text{C}$

$V_{CE}=1200\text{V}$, $V_{GE}=\pm 15\text{V}$, $R_{Gon}=47\Omega$, $R_{Goff}=3\text{ }3\Omega$

$t_{\text{sw}}[\mu\text{s}]$



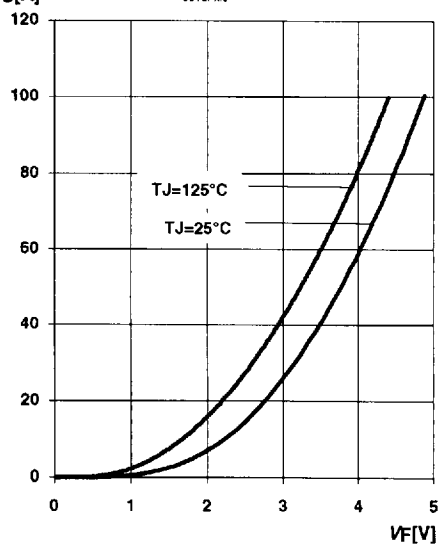
T.



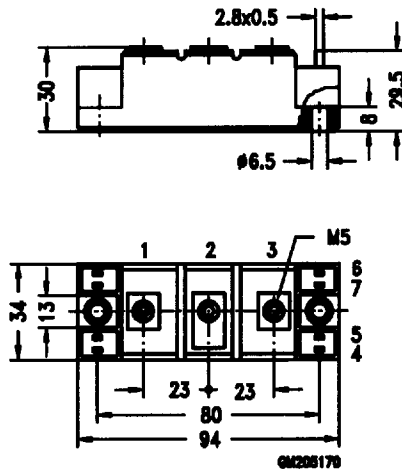
Forward characteristics of fast recovery reverse diode

$I_F=f(V_F)$, parameter: T_J

I_C [A]



Package Outlines and Configuration



Circuit

